Stackpole Electronics, Inc.

General Purpose High Power Thick Film Chip Resistor

Resistive Product Solutions

Features:

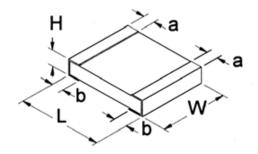
- High Power Rating
- Nickel Barrier terminations standard
- Power derating from 100% at 70°C to zero at +155°C
- RoHS compliant



Electrical Specifications									
Type / Code	Package Type	Power Rating (Watts) @ 70°C	Maximum Working Voltage (1)	Maximum Overload Voltage	Maximum Current	Resistance Temperature Coefficient	Ohmic Range (Ω) and Tolerance		
							1%	5%	
	0402	0.1W	50V	100V	1 Amp	± 200 ppm/°C	1 - 9.76	1 - 9.76	
RMCP0402						± 100 ppm/°C	10 - 1M	10 - 1M	
						± 200 ppm/°C	1.02M - 10M	1.02M - 10M	
	0603	0.125W	50V	100V	1 Amp	± 200 ppm/°C	1 - 9.76	1 - 9.76	
RMCP0603						± 100 ppm/°C	10 - 1M	10 - 1M	
						± 200 ppm/°C	1.02M - 10M	1.02M - 10M	
	0805	0.25W	150V	300V	2 Amp	± 200 ppm/°C	1 - 9.76	1 - 9.76	
RMCP0805						± 100 ppm/°C	10 - 1M	10 - 1M	
						± 200 ppm/°C	1.02M - 10M	1.02M - 10M	
	1206	0.33W	200V	400V	2 Amp	± 200 ppm/°C	1 - 9.76	1 - 9.76	
RMCP1206						± 100 ppm/°C	10 - 1M	10 - 1M	
						± 200 ppm/°C	1.02M - 10M	1.02M - 10M	
	1210	0.5W	200V	400V	3 Amp	± 200 ppm/°C	1 - 9.76	1 - 9.76	
RMCP1210						± 100 ppm/°C	10 - 1M	10 - 1M	
						± 200 ppm/°C	1.02M - 10M	1.02M - 10M	
RMCP2010	2010	1W	200V	400V	3 Amp	± 200 ppm/°C	1 - 9.76	1 - 9.76	
						± 100 ppm/°C	10 - 1M	10 - 1M	
						± 200 ppm/°C	1.02M - 10M	1.02M - 10M	
RMCP2512	2512	2W	200V	400V	3 Amp	± 200 ppm/°C	1 - 9.76	1 - 9.76	
						± 100 ppm/°C	10 - 1M	10 - 1M	
						± 200 ppm/°C	1.02M - 10M	1.02M - 10M	

⁽¹⁾ Lesser of √PR or maximum working voltage.

Please refer to the High Power Resistor Application Note (page 4) for more information on designing and implementing high power resistor types.



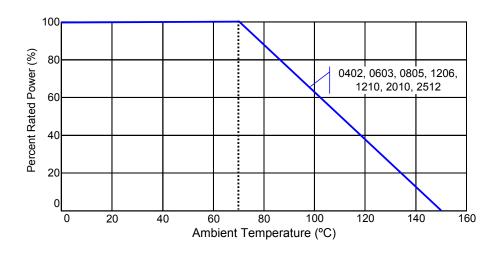
Mechanical Specifications									
Type / Code	L Body Length	W Body Width	H Body Height	a Top Termination	b Bottom Termination	Unit			
RMCP0402	0.039 ± 0.002	0.020 ± 0.002	0.014 ± 0.002	0.008 ± 0.004	0.008 ± 0.004	inches			
	1.00 ± 0.05	0.50 ± 0.05	0.35 ± 0.05	0.20 ± 0.10	0.20 ± 0.10	mm			
RMCP0603	0.063 ± 0.004	0.031 ± 0.004	0.018 ± 0.004	0.012 ± 0.008	0.012 ± 0.008	inches			
	1.60 ± 0.10	0.80 ± 0.10	0.45 ± 0.10	0.30 ± 0.20	0.30 ± 0.20	mm			
RMCP0805	0.079 ± 0.004	0.049 ± 0.004	0.020 ± 0.004	0.014 ± 0.008	0.016 ± 0.008	inches			
	2.00 ± 0.10	1.25 ± 0.10	0.50 ± 0.10	0.35 ± 0.20	0.40 ± 0.20	mm			
RMCP1206	0.122 ± 0.004	0.061 ± 0.004	0.021 ± 0.004	0.020 ± 0.010	0.020 ± 0.008	inches			
	3.10 ± 0.10	1.55 ± 0.10	0.55 ± 0.10	0.50 ± 0.25	0.50 ± 0.20	mm			
RMCP1210	0.122 ± 0.004	0.102 ± 0.006	0.021 ± 0.004	0.020 ± 0.010	0.020 ± 0.008	inches			
	3.10 ± 0.10	2.60 ± 0.15	0.55 ± 0.10	0.50 ± 0.25	0.50 ± 0.20	mm			
RMCP2010	0.197 ± 0.004	0.098 ± 0.006	0.021 ± 0.004	0.024 ± 0.010	0.020 ± 0.008	inches			
	5.00 ± 0.10	2.50 ± 0.15	0.55 ± 0.10	0.60 ± 0.25	0.50 ± 0.20	mm			
RMCP2512	0.250 ± 0.004	0.122 ± 0.006	0.021 ± 0.004	0.024 ± 0.010	0.020 ± 0.008	inches			
	6.35 ± 0.10	3.10 ± 0.15	0.55 ± 0.10	0.60 ± 0.25	0.50 ± 0.20	mm			

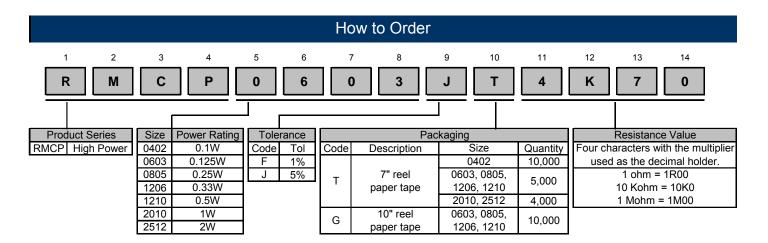
Performance Characteristics								
Test	Test Conditions (JIS C 5202)	Test Results						
Short Time Overload	2.5x rated voltage for 5 seconds	± (2% + 0.1Ω)						
Dielectric Withstanding Voltage	100 VAC, 1 minute	± (1% + 0.05Ω)						
Resistance to Soldering Heat	260°C ±5°C, for 10 sec. ±0.5 sec. (Solder Bath)	± (1% + 0.05Ω)						
Solderability	235°C ±5°C, for 2 sec. ±0.5 sec. (Colophonium flux)	95% coverage, minimum						
Temperature Cycle	-65°C: 30 min. 25°C: 2 to 3 min. 155°C: 30 min. 25°C: 2 to 3 min. (5 Cycles)	\pm (1% + 0.05Ω) Jumper (<0.05Ω)						
Endurance (Damp load)	40°C ± 2°C, 90% RH, Rated Load 90 min. On, 30 min. Off for 1,000 hrs0hrs./+48hrs.	±(3% + 0.1Ω) Jumper (<0.05Ω)						
Endurance (Rated load)	70°C ± 2°C, Rated Load 90 min. On, 30 min. Off for 1,000 hrs0hrs./+48hrs.	\pm (3% + 0.1Ω) Jumper (<0.05Ω)						
Voltage Coefficient	1/10 rated voltage for 3 sec. max. then rated voltage for 3 sec. max.	±100 (ppm/V)						
Robustness of Termination	Bend of 3mm for 5 ± 1 sec.	± (1% + 0.05 Ohm)						

Operating Temperature Range: -55°C - 155°C

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Power Derating Curve:





Legacy Part Number (before January 3, 2011):

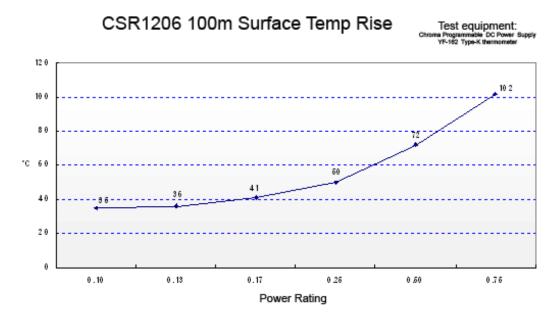
SEI Type				Nominal Resistance	Tolera			Packaging R				
Type	Description	Code	Wattage	Size		Tolerance	Values	SEI Types	Pkg Qty	Description	Code	
RMCP	High Power	0402	0.1W	0402		1%	E96,E24	0402	10,000	7" reel - paper tape	R	
' <u>-</u>		0603	0.125W	0603		5%	E24	0603, 0805,	10,000	10" reel - paper tape	G	
		0805	0.25W	0805				1206, 1210	10,000	10 Teel - papel tape		
		1206	0.33W	1206				0603, 0805,	5,000	7" reel - paper tape	R	
		1210	0.5W	1210				1206, 1210	5,000			
		2010	1W	2010				2010, 2512	4,000			
		2512	2W	2512				•	•			

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High Power Chip Resistors and Thermal Management

Stackpole has developed several surface mount resistor series in addition to our current sense resistors, which have had higher power ratings than standard resistor chips. This has caused some uncertainty and even confusion by users as to how to reliably use these resistors at the higher power ratings in their designs.

The data sheets for the RHC, RMCP, RNCP, CSR, CSRN, CSRF, CSS, and CSSH state that the rated power assumes an ambient temperature of no more than 100 degrees C for the CSS / CSSH series and 70 degrees C for all other high power resistor series. In addition, IPC and UL best practices dictate that the combined temperature on any resistor due to power dissipated and ambient air shall be no more than 105C. At first glance this wouldn't seem too difficult, however the graph below shows typical heat rise for the CSR 100 milliohm at full rated power. The heat rise for the RMCP and RNCP would be similar. The RHC with its unique materials, design, and processes would have less heat rise and therefore would be easier to implement for any given customer.



The 102 degrees C heat rise shown here would indicate there will be additional thermal reduction techniques needed to keep this part under 105C total hot spot temperature if this part is to be used at 0.75 watts of power. However, this same part at the usual power rating for this size would have a heat rise of around 72 degrees C. This additional heat rise may be dealt with using wider conductor traces, larger solder pads and land patterns under the solder mask, heavier copper in the conductors, vias through PCB, air movement, and heat sinks, among many other techniques. Because of the variety of methods customers can use to lower the effective heat rise of the circuit, resistor manufacturers simply specify power ratings with the limitations on ambient air temperature and total hot spot temperatures and leave the details of how to best accomplish this to the design engineers. Design guidelines for products in various market segments can vary widely so it would be unnecessarily constraining for a resistor manufacturer to recommend the use of any of these methods over another.

Note: The final resistance value can be affected by the board layout and assembly process, especially the size of the mounting pads and the amount of solder used. This is especially notable for resistance values $\leq 50~\text{m}\Omega$. This should be taken into account when designing.